



Material Content Data Sheet



Sales Product Name	TLE4205G			Issued	24. January 2018			
MA#	MA001189214							
Package	PG-DSO-20-66			Weight*	486.69 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.461	1.12	1.12	11221	11221
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6378	
wire	non noble metal	copper	7440-50-8	126.041	25.90	26.58	258976	265753
	non noble metal	copper	7440-50-8	0.167	0.03	0.03	344	344
	encapsulation	organic material	carbon black	1333-86-4	0.690	0.14		1418
encapsulation	plastics	epoxy resin	-	31.752	6.52		65240	
	inorganic material	silicondioxide	60676-86-0	312.688	64.27	70.93	642475	709133
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5642	5642
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3331	3331
glue	plastics	epoxy resin	-	0.557	0.11		1144	
	noble metal	silver	7440-22-4	1.671	0.34	0.45	3432	4576
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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